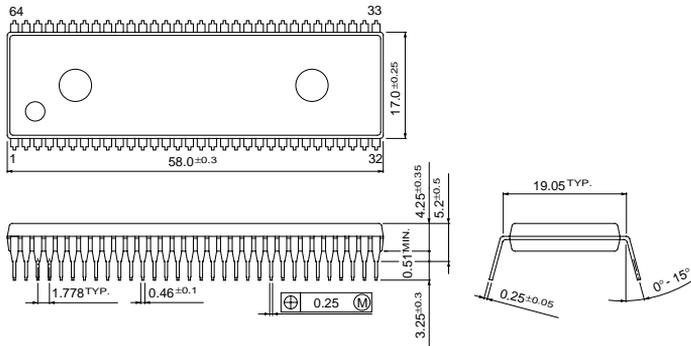


Package Outline

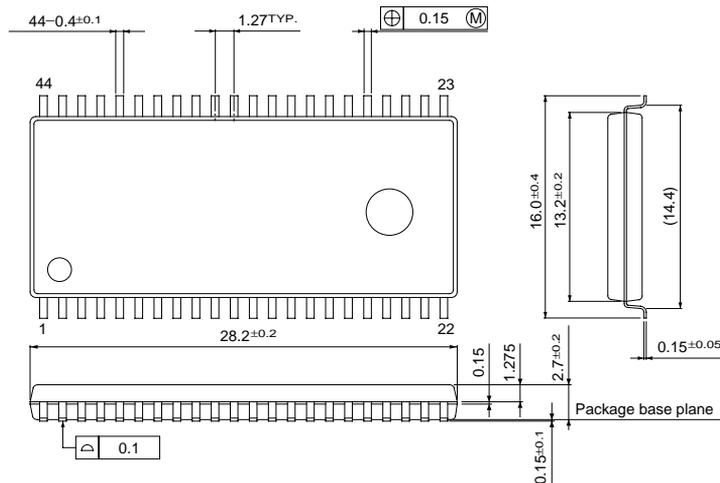
(Unit : mm)

64 SDIP (SDIP064-P-0750)

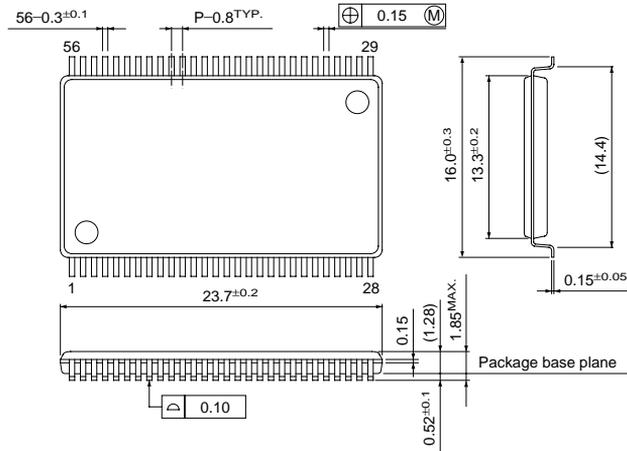


- SDIP : Shrink DIP*
- SOP : Small Outline Package
- SSOP: Shrink SOP
- TSOP: Thin SOP
- CSP : Chip Size Package (FBGA)
- *DIP : Dual In-line Package

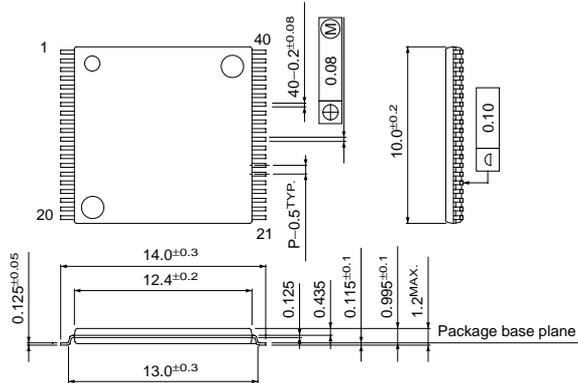
44 SOP (SOP044-P-0600)



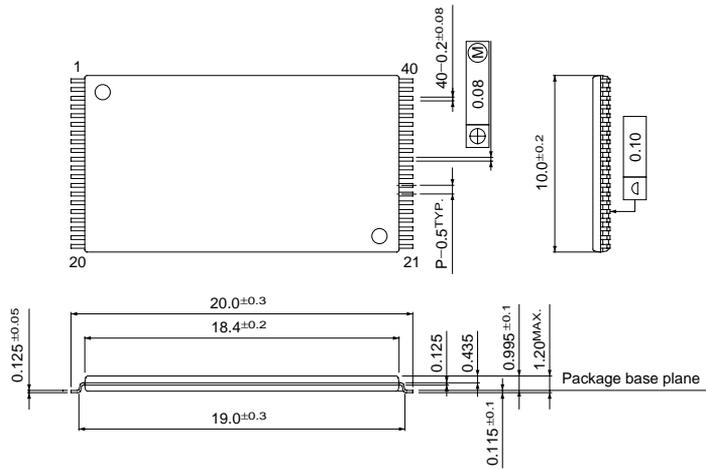
56 SSOP (SSOP056-P-0600)



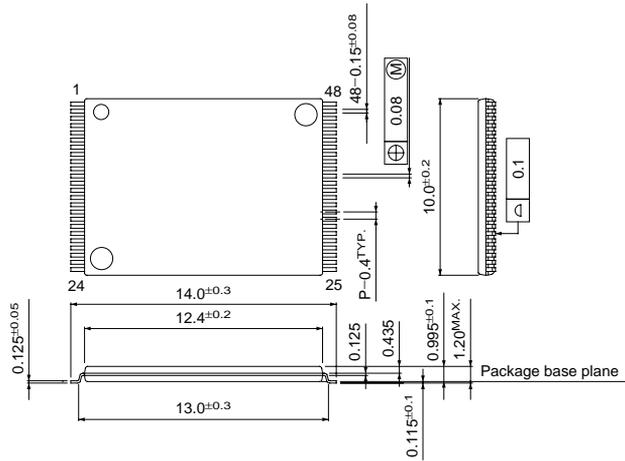
40 TSOP (TSOP040-P-1014)



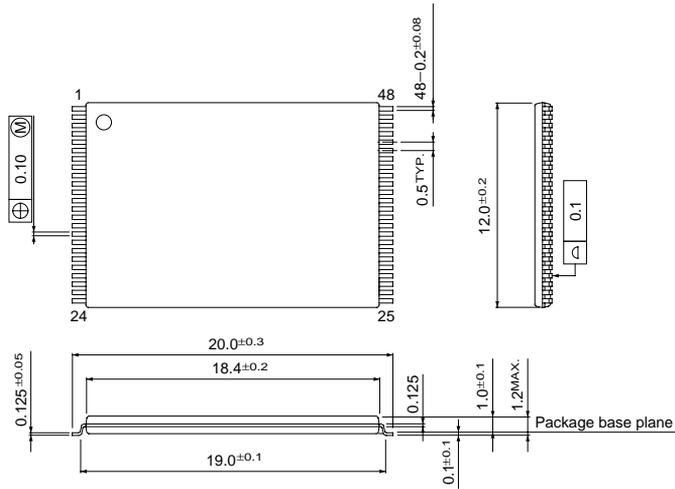
40 TSOP (TSOP040-P-1020)



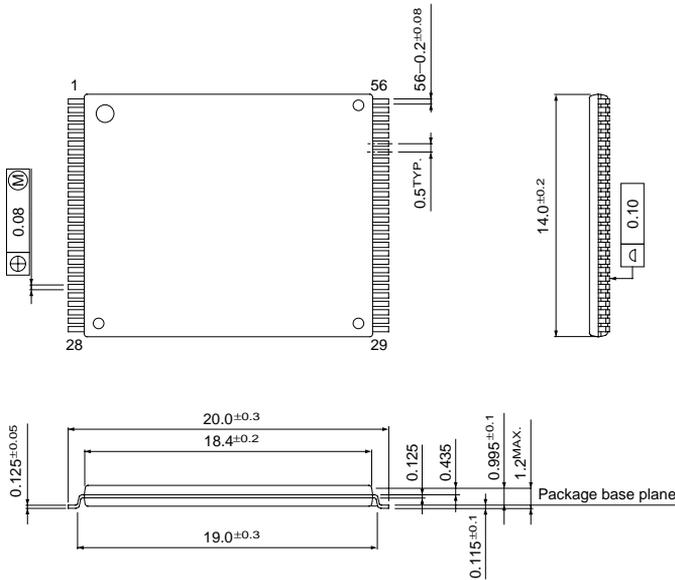
48 TSOP (TSOP048-P-1014)



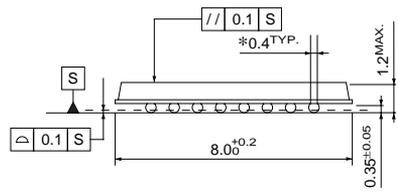
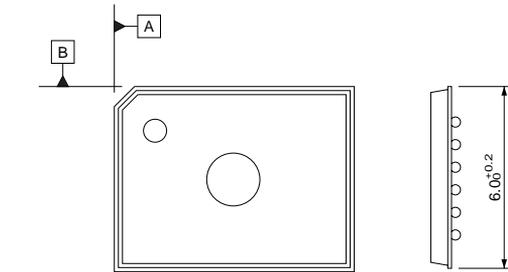
48 TSOP (TSOP048-P-1220)



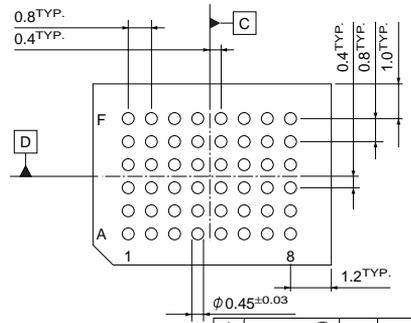
56 TSOP (TSOP056-P-1420)



48 CSP (FBGA048-P-0608)

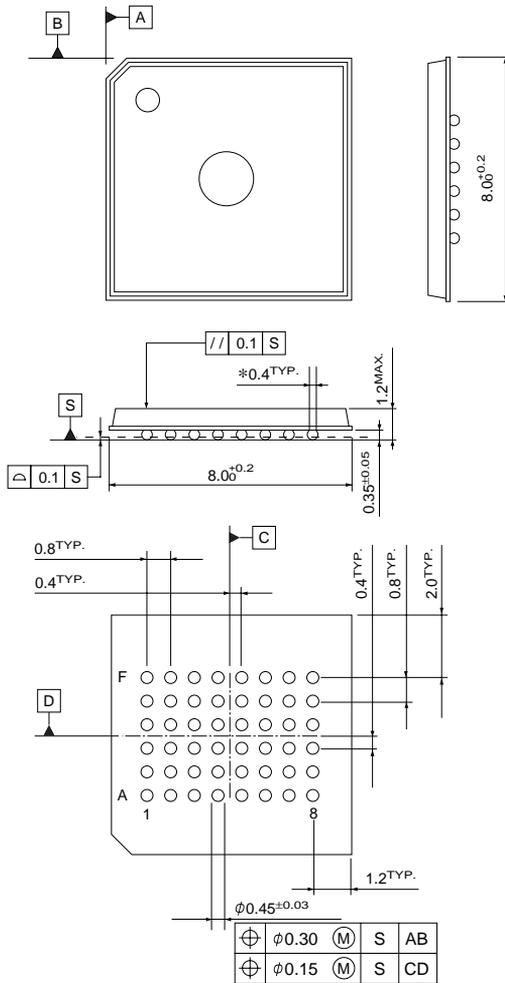


*Land hole diameter for ball mounting



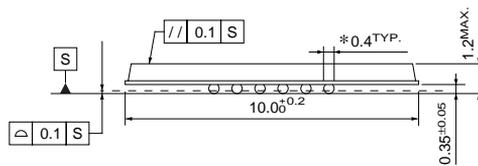
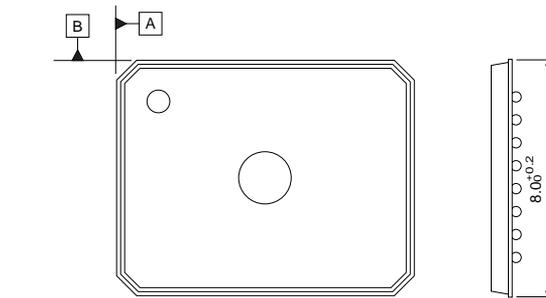
⊕	φ0.30	(M)	S	AB
⊕	φ0.15	(M)	S	CD

48 CSP (FBGA048-P-0808)

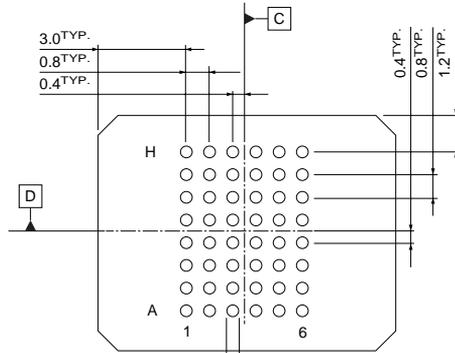


*Land hole diameter for ball mounting

48 CSP (FBGA048-P-0810)

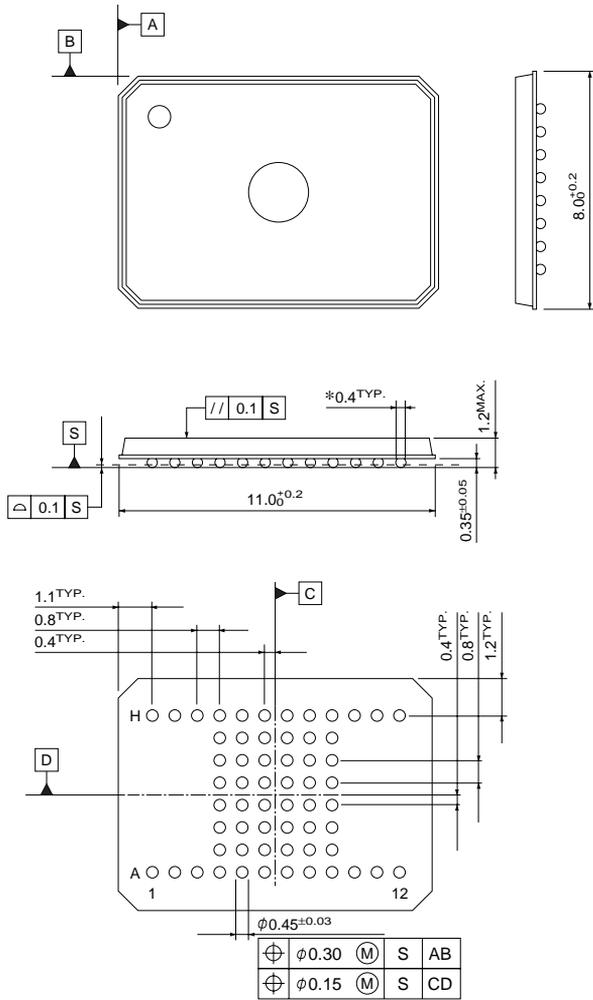


*Land hole diameter for ball mounting



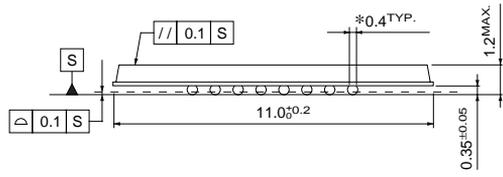
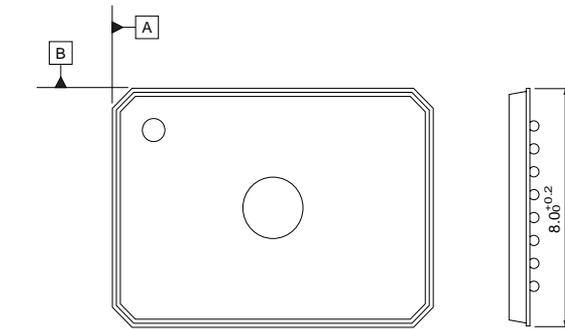
⊕	φ 0.30	(M)	S	AB
⊕	φ 0.15	(M)	S	CD

60 CSP (FBGA060/048-P-0811)

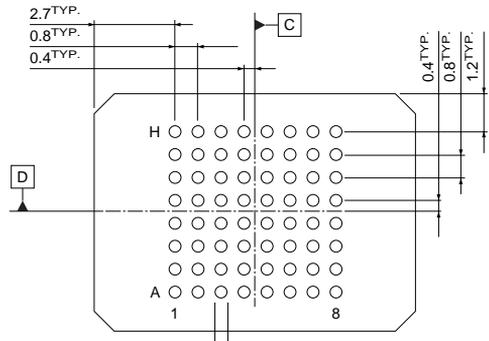


*Land hole diameter for ball mounting

64 CSP (FBGA064-P-0811)



*Land hole diameter for ball mounting



$\phi 0.45 \pm 0.03$

ϕ	$\phi 0.30$	(M)	S	AB
ϕ	$\phi 0.15$	(M)	S	CD

80 CSP (FBGA080/064-P-0818)

